



Line-up
for
Network

Multi-layer circuit board materials for ICT infrastructure equipment

ICTインフラ機器向け多層基板材料

*ICT...Information and Communication Technology

Applications 用途

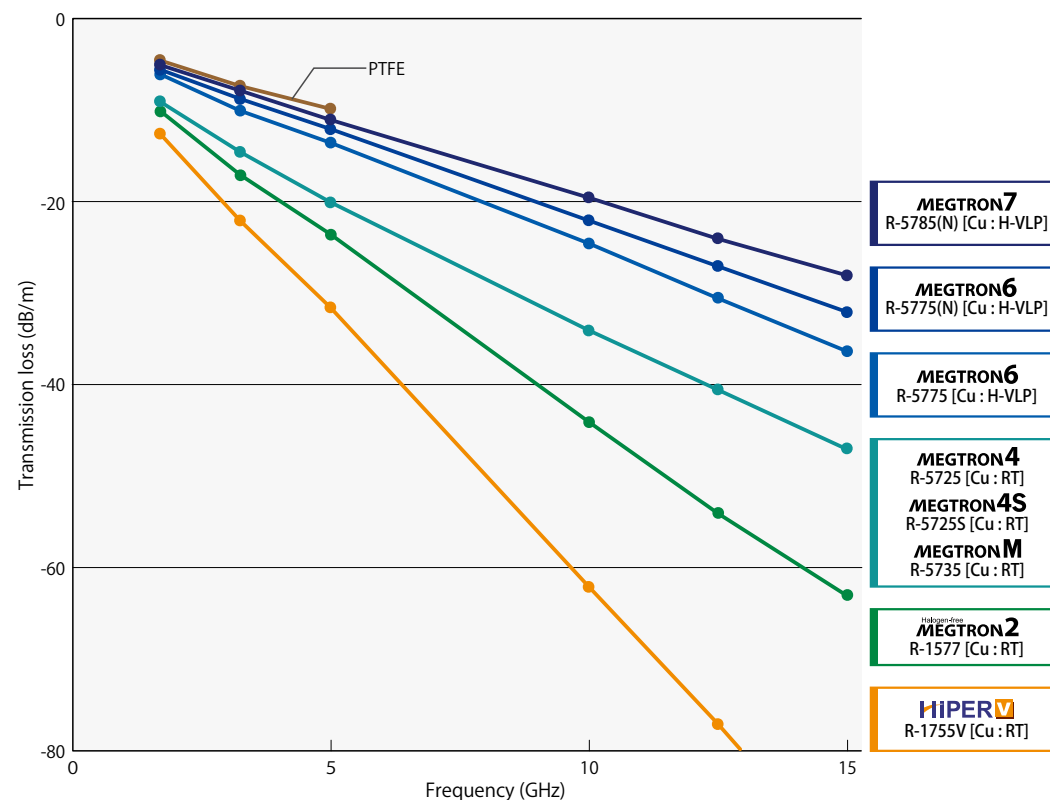
Server, Router, Switch, Supercomputer, Measuring instrument, Etc.

サーバ、ルータ、スイッチ、スーパーコンピュータ、半導体検査装置など

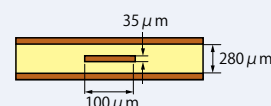
Multi-layer circuit board materials suitable to large capacity and high speed transmission of high frequency signal.

高周波信号などの大容量・高速伝送に対応する多層基板材料

Line-up ラインアップ



Construction



Core	0.13mm
Prepreg	0.06mm x 2ply
Line length	1m
Cu thickness	t=35 μm
Impedance	50Ω

General properties 一般特性

Item	Test method	Unit	MEGTRON7	MEGTRON6		MEGTRON4	MEGTRON4S	MEGTRONM	MEGTRON2	HIPERV
			R-5785(N)	R-5775(N)	R-5775	R-5725	R-5725S	R-5735	R-1577	R-1755V
Glass transition temp.(Tg)	DSC	°C	200	185	185	176	200	195	170	173
CTE z-axis	α 1	ppm/°C	42	45	45	35	32	31	34	44
			280	260	260	265	250	240	200	255
T288(with copper)	IPC-TM-650 2.4.24.1	min	>120	>120	>120	30	50	35	25	20
Dielectric constant(Dk) ^{*1}	1GHz	—	3.4	3.4	3.7	3.8	3.8	3.9	4.1	4.4
Dissipation factor(Df) ^{*1}			0.001	0.002	0.002	0.005	0.005	0.005	0.010	0.016
Peel strength ^{*2}	1oz(35 μm)	kN/m	0.8	0.8	0.8	1.1	1.3	1.2	1.3	1.5

The sample thickness of MEGTRON7, MEGTRON6 is 0.75mm. The sample thickness of other part number is 0.8mm.

<Condition> As received. ^{*1} C-24/23/50

^{*2} MEGTRON7, MEGTRON6 is H-VLP copper. MEGTRON4, MEGTRON4S, MEGTRON M is RT copper. MEGTRON2, HIPER V is ST copper.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others. 当社ハロゲンフリー材料は、JPCA-ES-01-2003などの定義によるものです。The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。

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